Addendum

HC908JB16AD/D
Rev. 1, 8/2002

Addendum to
MC68HC908JB16
Technical Data

This addendum provides update and additional information to the

MC68HC908JB16 Technical Data, Rev. 1
(Motorola document number MC68HC908JB16/D),

pertaining to the following:

- MC68HC908JB16
  - Update to V_{REG} LVI trip point
  - 20-pin SOIC package
- MC68HC908JB12
- MC68HC08JB16

MC68HC908JB16

This section updates data sheet information and introduces the 20-pin SOIC package for the MC68HC908JB16.

V_{REG} LVI Trip Point

Page 318, entry for minimum V_{REG} LVI trip point voltage has been updated.

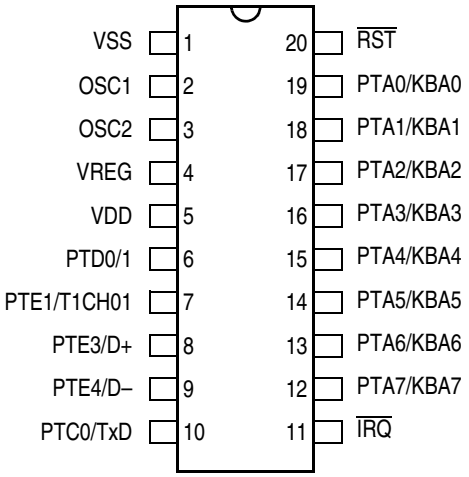
From:

Characteristic	Symbol	Min	Typ	Max	Unit
V_{REG} LVI trip point voltage	V_{LVR}	2.0	2.2	2.6	V

To:

V_{REG} LVI trip point voltage	V_{LVR}	**1.9**	2.2	2.6	V

20-Pin SOIC *Order Number:* ***MC68HC908JB16JDW***

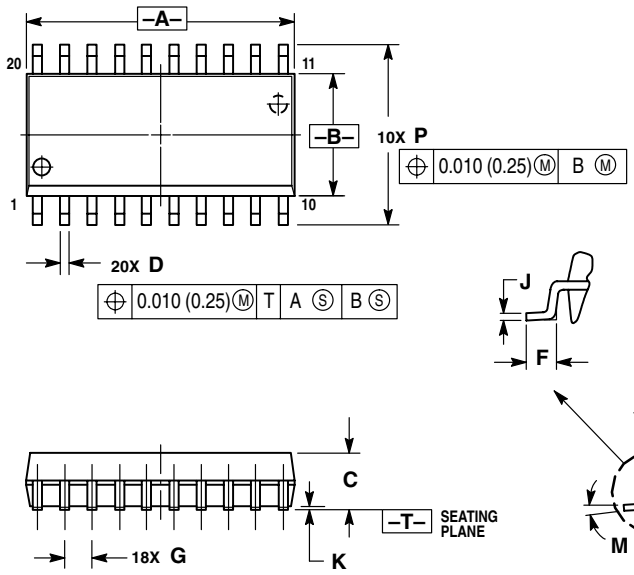


Pins not available on 20-pin package:		
PTC1/RxD	PTE0/TCLK	PTD2
	PTE2/T2CH01	PTD3
CGMXFC1	CGMXFC2	PTD4
CGMOUT1	CGMOUT2	PTD5
VREGA0	VREGA1	
VSSA0	VSSA1	VDDA

Internal pads are unconnected.

PTD0/1 pin: PTD0 and PTD1 internal pads are bonded together to PTD0/1 pin, and has 50mA sink capability when configured as an output. Pin direction must be configured such that DDRD0 = DDRD1.

Figure 1. 20-Pin SOIC Pin Assignment



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.150 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	12.65	12.95	0.499	0.510
B	7.40	7.60	0.292	0.299
C	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.50	0.90	0.020	0.035
G	1.27 BSC		0.050 BSC	
J	0.25	0.32	0.010	0.012
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029

Figure 2. 20-Pin SOIC Mechanical Dimensions (Case No. 751D)

MC68HC908JB12

This section introduces the MC68HC908JB12, a derivative of the MC68HC908JB16. The entire MC68HC908JB16 data book, including the updates in this addendum, applies to this device, with exceptions outlined below.

Table 1. Summary of MC68HC908JB12 and MC68HC908JB16 Differences

	MC68HC908JB12	MC68HC908JB16
FLASH Memory	12,288 bytes ($CA00–$F9FF)	16,384 bytes ($BA00–$F9FF)
Dual Clock Generator Module	Not implemented. $0051–$0059 unimplemented.	Available in 32-pin LQFP only.
Available Packages(1)	— 28-pin SOIC 20-pin SOIC	32-pin LQFP 28-pin SOIC 20-pin SOIC

Notes:
1. The pin assignments are identical for both devices; see data sheet.

MCU Block Diagram

Figure 3 shows the structure of the MC68HC908JB12.

Memory Map

Figure 4 shows the memory map of the MC68HC908JB12.

Dual Clock Generator Module

The dual 27-MHz clock generator module on the MC68HC908JB16 is not designed in the MC68HC908JB12, hence, register locations from $0051 to $0059 are unimplemented. Information in the data book relating to the CGM do not apply to the MC68HC908JB12.

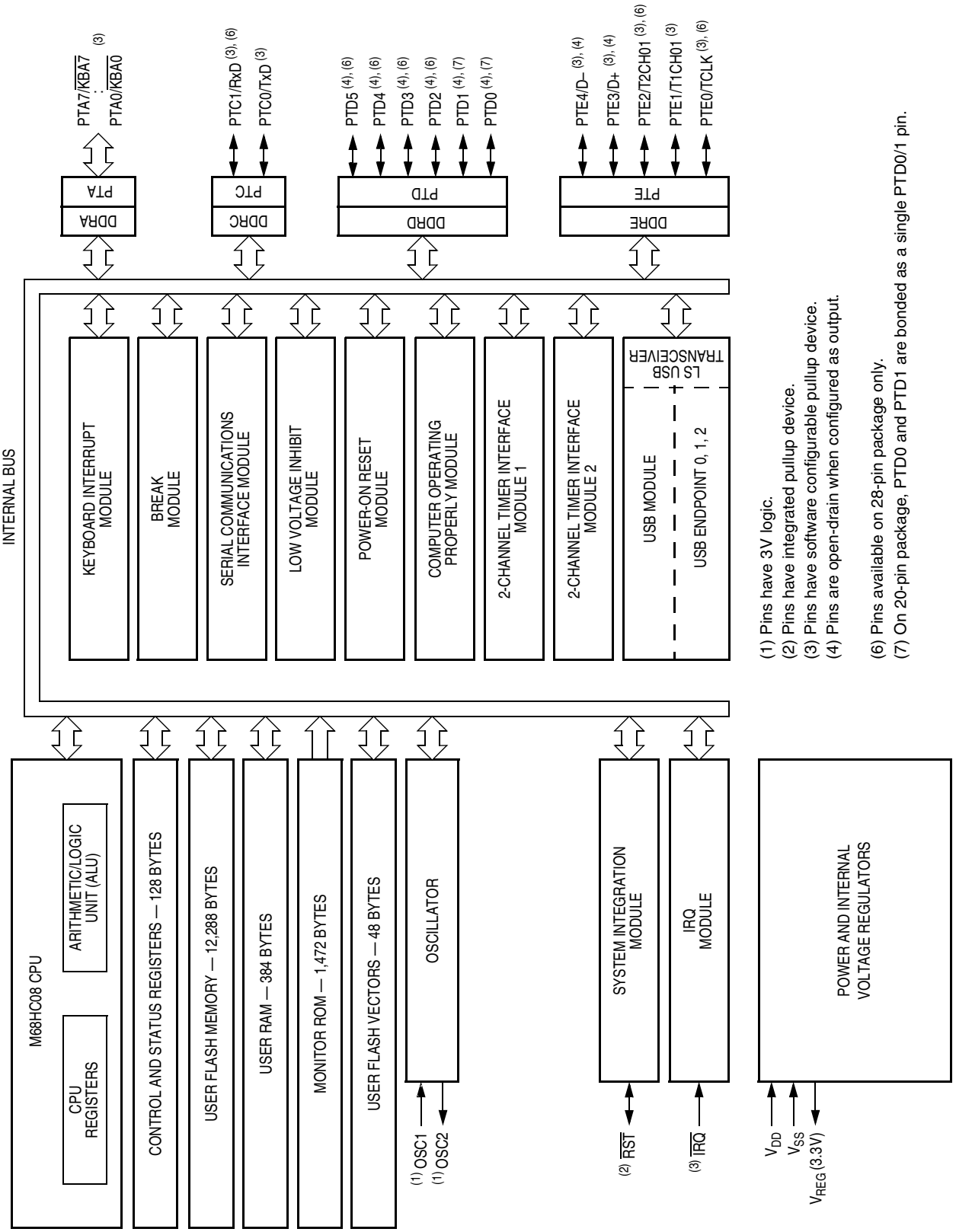


Figure 3. MC68HC908JB12 Block Diagram

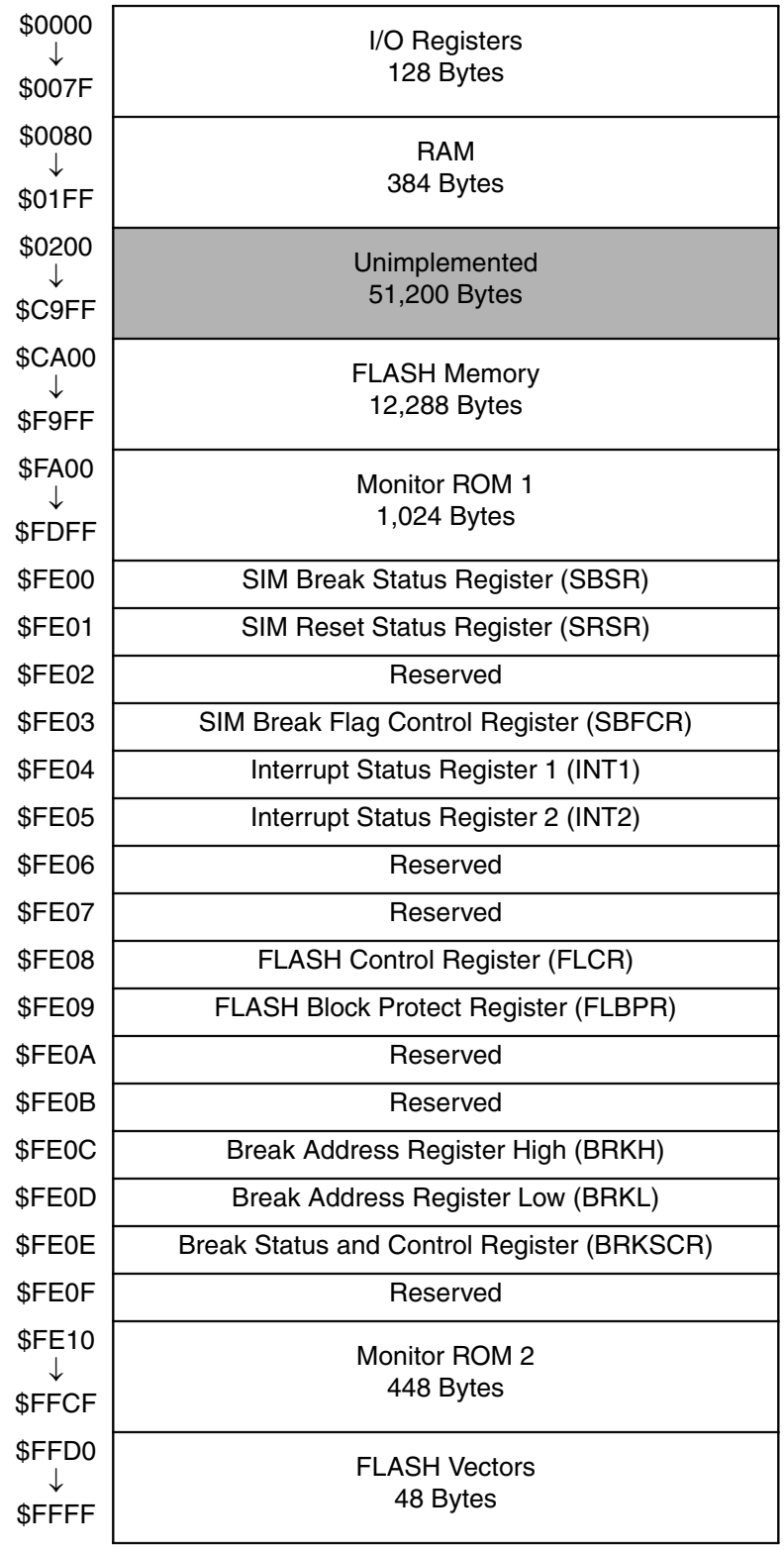


Figure 4. MC68HC908JB12 Memory Map

Pullup on PTE3/D+ and PTE4/D– Pins

On the MC68HC908JB12, control over the pullup devices on PTE3/D+ and PTE4/D– pins are shown in **Table 2**.

Table 2. Pullup Control on PTE3/D+ and PTE4/D– Pins

PULLEN ($001A)	USBEN ($0038)	PTExP ($001D)	PTE4IE ($001C)	PTE3/D+ pin	PTE4/D– pin
0	0	0	0	—	—
0	0	1	0	5kΩ pullup to V_{DD}	5kΩ pullup to V_{DD}
0	0	0	1	—	5kΩ pullup to V_{DD} (1)
0	0	1	1	5kΩ pullup to V_{DD}	5kΩ pullup to V_{DD} (1)
0	1	X	X	—	—
1	1	X	X	—	1.5kΩ pullup to V_{REG}
1	0	X	0	—	1.5kΩ pullup to V_{REG}
1	0	X	1	Do not set this configuration.	

Notes:

1. External interrupt function is also enabled on PTE4/D– pin.

Electrical Specifications

Electrical specifications for the MC68HC908JB16 apply to the MC68HC908JB12, except for the USB reset timing:

Bus State	Signaling Levels	
	Transmit	Receive
Reset	NA	D+ and D– < V_{IL} (max) for ≥ 8μs (MC68HC908JB16) D+ and D– < V_{IL} (max) for ≥ 125μs (MC68HC908JB12)

Order Numbers

These are MC order numbers for MC68HC908JB12.

Table 3. MC68HC908JB12 Order Numbers

MC Order Number	Package	Operating Temperature Range
MC68HC908JB12JDW	20-pin SOIC	0 °C to +70 °C
MC68HC908JB12DW	28-pin SOIC	0 °C to +70 °C

MC68HC08JB16

This section introduces the MC68HC08JB16, the ROM part equivalent to the MC68HC908JB16. The entire MC68HC908JB16 data book applies to this ROM device, with exceptions outlined below.

Table 4. Summary of MC68HC08JB16 and MC68HC908JB16 Differences

	MC68HC08JB16	MC68HC908JB16
Memory ($BA00–$F9FF)	16,384 bytes ROM	16,384 bytes FLASH
User vectors ($FFD0–$FFFF)	48 bytes ROM	48 bytes FLASH
Registers at $FE08 and $FE09	Not used; locations are reserved	FLASH related registers. $FE08 — FLCR $FE09 — FLBPR
Monitor ROM 1 ($FA00–$FDFF)	Unimplemented	Used for testing and FLASH programming/erasing.
Monitor ROM 2 ($FE10–$FFCF)	Used for testing purposes only.	
Dual Clock Generator Module	Currently not available.	Available in 32-pin LQFP only.
Available Packages(1)	32-pin LQFP currently not available. 28-pin SOIC 20-pin SOIC	32-pin LQFP 28-pin SOIC 20-pin SOIC

Notes:
1. The pin assignments are identical for both devices; see data sheet.

MCU Block Diagram

Figure 5 shows the block diagram of the MC68HC08JB16.

Memory Map

Figure 6 shows the memory map of the MC68HC08JB16.

Reserved Registers

The two registers at $FE08 and $FF09 are reserved locations on the MC68HC08JB16.

On the MC68HC908JB16, these two locations are the FLASH control register and the FLASH block protect register respectively.

Monitor ROM

The monitor program (monitor ROM, $FE10–$FFCF) on the MC68HC08JB16 is for device testing only.

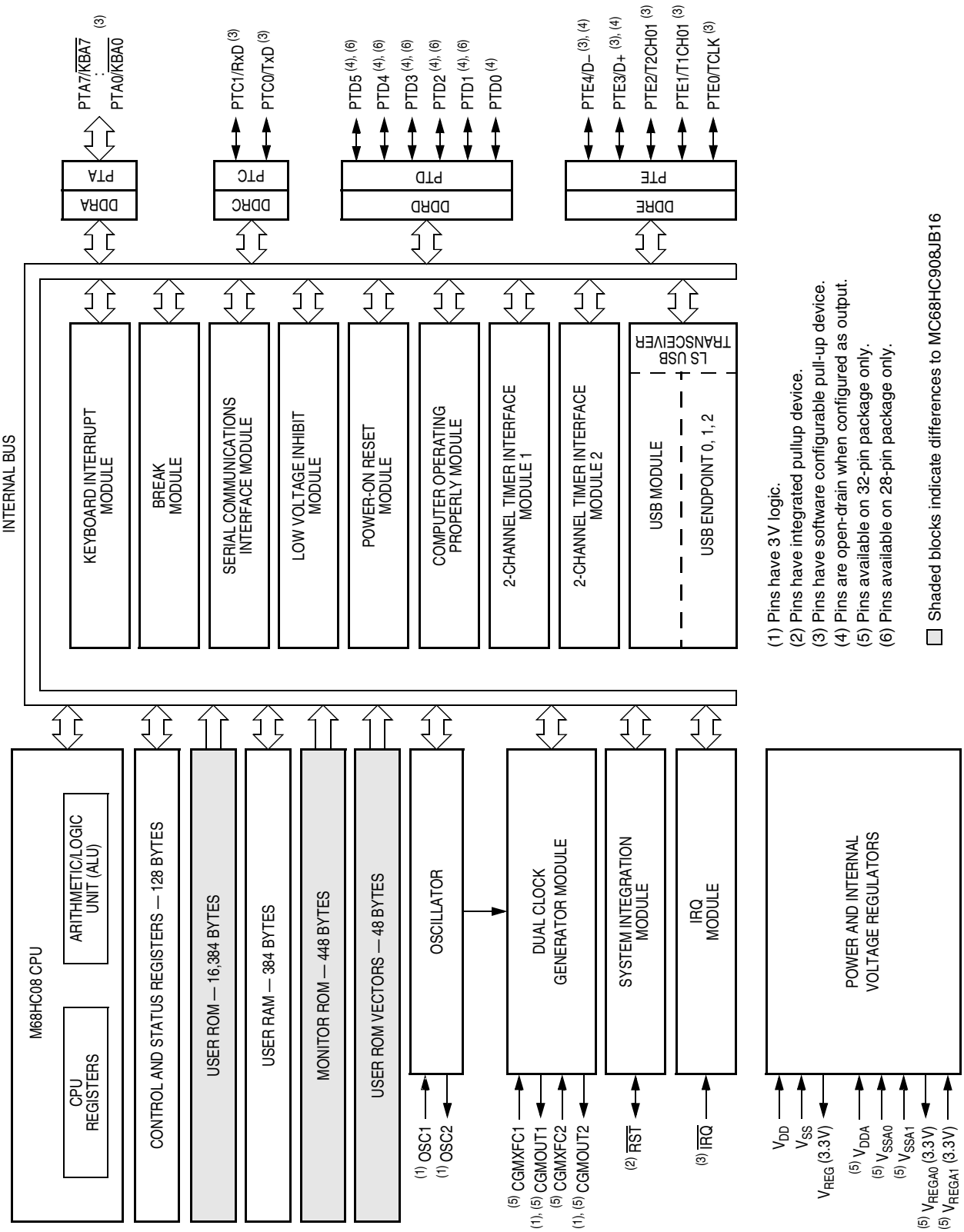


Figure 5. MC68HC08JB16 Block Diagram

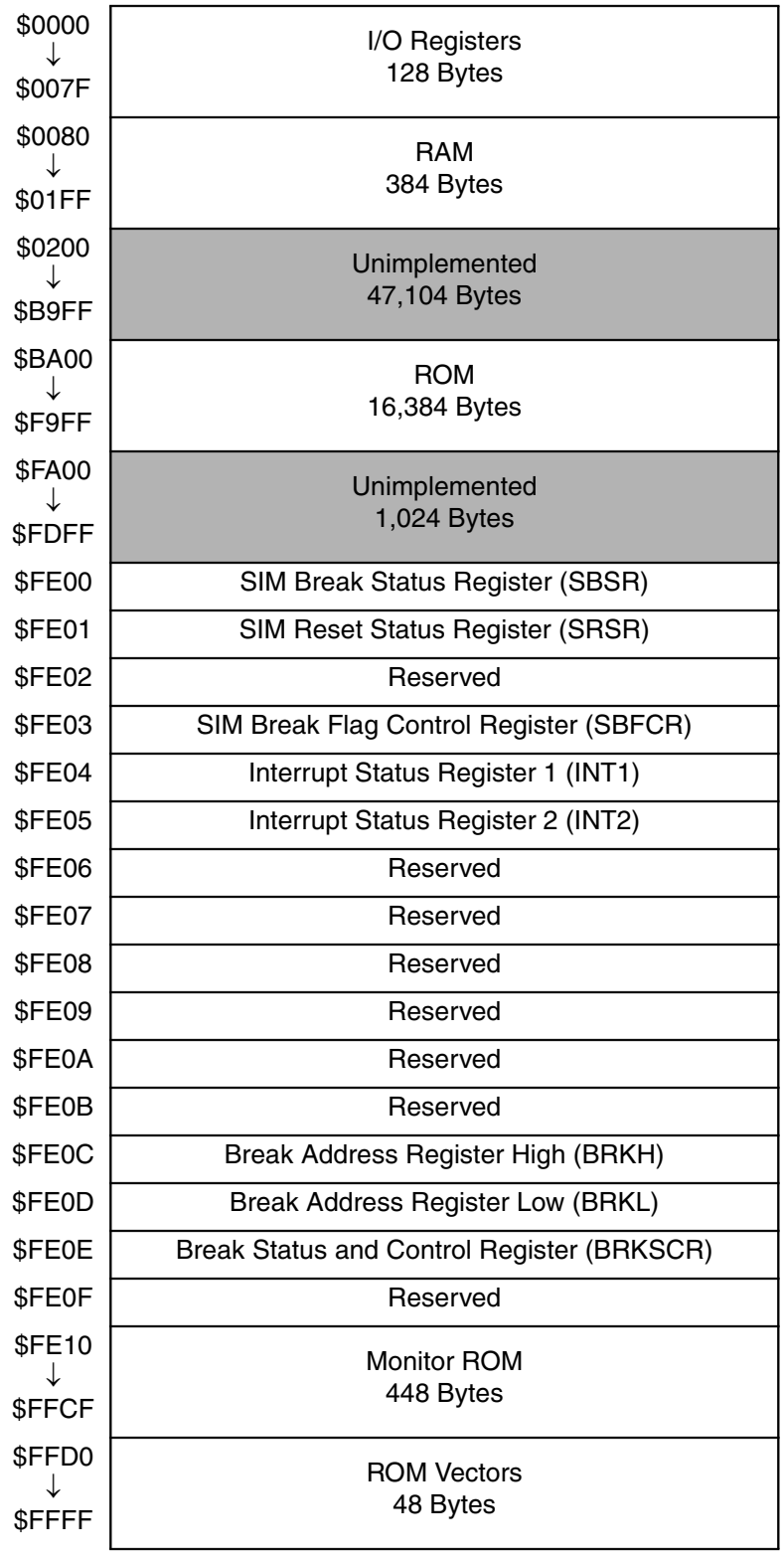


Figure 6. MC68HC08JB16 Memory Map

Electrical Specifications

Electrical specifications for the MC68HC908JB16 apply to the MC68HC08JB16, except for the following:

FLASH Memory Characteristics

The FLASH memory electrical characteristics do not apply to the MC68HC08JB16 ROM device.

ROM MC Order Numbers

These part numbers are generic numbers only. To place an order, ROM code must be submitted to the ROM Processing Center (RPC).

Table 5. ROM MC Order Numbers

MC Order Number	Package	Operating Temperature Range
MC68HC08JB16JDW	20-pin SOIC	0 °C to +70 °C
MC68HC08JB16DW	28-pin SOIC	0 °C to +70 °C

NOTES

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